



EFW/B

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PATENT

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

INVENTOR Edmund D. Blackshear ) EXAMINER: A. O. Williams  
SERIAL NO: 10/719,334 ) ART UNIT: 2826  
FILING DATE: November 21, 2003 ) DATE: December 28, 2005  
TITLE: OVERLAP STACKING OF CENTER BUS BONDED MEMORY  
CHIPS FOR DOUBLE DENSITY AND METHOD OF  
MANUFACTURING THE SAME

**TRANSMITTAL OF FORMAL DRAWINGS**


Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450  
**ATTN: OFFICIAL DRAFTSPERSON**

Dear Sir:

Enclosed are formal drawings for the above-identified application. Kindly replace the informal drawings, as filed, with the enclosed 4 sheets of drawings marked "REPLACEMENT SHEETS." No new matter has been added.

Please charge the Assignee IBM Corporation Deposit Account No. **09-0458** for any fee related to the acceptance of the attached Formal Drawings. A duplicate copy of this letter is enclosed for that purpose.

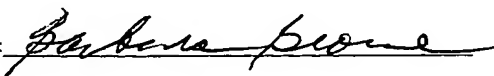
Respectfully submitted,

  
Robert Curcio  
Reg. No. 44,638

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New Haven, CT 06510-1241

**CERTIFICATE OF MAILING UNDER 37 CFR 1.8**

I hereby certify that I am depositing the enclosed or attached correspondence with the United States Postal Service as first class mail in an envelope addressed to the, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, ATTENTION OFFICIAL DRAFTSPERSON.

Name of person mailing paper Barbara Browne Date: December 28, 2005 Signature:   
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